SDAS022C - DECEMBER 1982 - REVISED JANUARY 1995

- High Capacitive-Drive Capability
- 'ALS804A Has Typical Delay Time of 4 ns (C_L = 50 pF) and Typical Power Dissipation of 3.4 mW Per Gate
- 'AS804B Has Typical Delay Time of 2.6 ns (C_L = 50 pF) and Typical Power Dissipation of Less Than 9 mW Per Gate
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

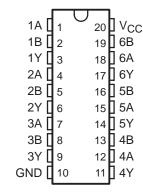
These devices contain six independent 2-input NAND drivers. They perform the Boolean functions $Y = \overline{A} \cdot \overline{B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The SN54ALS804A and SN54AS804B are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS804A and SN74AS804B are characterized for operation from 0°C to 70°C.

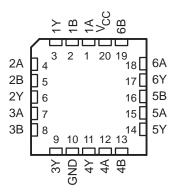
FUNCTION TABLE (each driver)

INP	UTS	OUTPUT
Α	В	Υ
Н	Н	L
L	Χ	Н
Х	L	Н

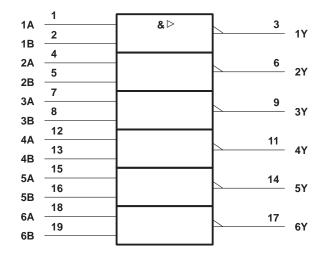
SN54ALS804A, SN54AS804B . . . J PACKAGE SN74ALS804A, SN74AS804B . . . DW OR N PACKAGE (TOP VIEW)



SN54ALS804A, SN54AS804B . . . FK PACKAGE (TOP VIEW)

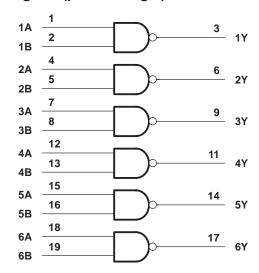


logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Operating free-air temperature range, T _A : SN54ALS804A	
SN74ALS804A	0°C to 70°C
Storage temperature range	-65°C to 150°C

recommended operating conditions

		SN5	4ALS80	4A	SN7	SN74ALS804A		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			8.0	V
ІОН	High-level output current			-12			-15	mA
l _{OL}	Low-level output current			12			24	mA
T _A	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	7507.00	ALDITIONS.	SN5	4ALS80	4A	SN7	4ALS80	4A	LINUT
PARAMETER	TEST CO	INDITIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2			V _{CC} -2			
V		$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V
VOH	V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2						V
		$I_{OH} = -15 \text{ mA}$				2			
V	V 45V	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
VoL	V _{CC} = 4.5 V	I _{OL} = 24 mA					0.35	0.5	V
lį	$V_{CC} = 5.5 \text{ V},$	$V_I = 7 V$			0.1			0.1	mA
lн	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ
Ι _Ι L	$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V			-0.1			-0.1	mA
Ι _Ο §	$V_{CC} = 5.5 \text{ V},$	V _O = 2.25 V	-20		-112	-30		-112	mA
ICCH	$V_{CC} = 5.5 \text{ V},$	V _I = 0		0.9	2.5		0.9	2.5	mA
ICCL	$V_{CC} = 5.5 \text{ V},$	V _I = 4.5 V		7	12		7	12	mA

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	$\begin{array}{c} \text{V}_{\text{CC}} = 4.5 \text{ V tr} \\ \text{C}_{\text{L}} = 50 \text{ pF}, \\ \text{TO} \\ \text{(OUTPUT)} \\ \end{array}$		=, 	,	UNIT	
	, ,	,	SN54AL	S804A	SN74AL	S804A	
			MIN	MAX	MIN	MAX	
t _{PLH}	A or B	V	2	9	2	7	ns
^t PHL	AUID	ſ	2	9	2	8	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}		 7 V
Input voltage, V _I		 7 V
Operating free-air temperature range, TA:	SN54AS804B	 55°C to 125°C
	SN74AS804B	 0°C to 70°C
Storage temperature range		 65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions§

		SN	54AS804	4B	SN	SN74AS804B			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage	2			2			V	
V_{IL}	Low-level input voltage			8.0			8.0	V	
IOH	High-level output current			-40			-48	mA	
lOL	Low-level output current			40			48	mA	
TA	Operating free-air temperature	-55		125	0		70	°C	

[§] These high sink- or source-current devices are not recommended for use above 40 MHz.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			SN	54AS80	4B	SN	74AS804	4B	LINUT
PARAMETER	TEST CO	ONDITIONS	MIN	TYP [†]	MAX	MIN	TYP†	MAX	UNIT
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2			
V		$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V
VOH	V _{CC} = 4.5 V	$I_{OH} = -40 \text{ mA}$	2						V
		$I_{OH} = -48 \text{ mA}$				2			
V	\/ 45\/	$I_{OL} = 40 \text{ mA}$		0.25	0.5				V
VOL	V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$					0.35	0.5	V
lį	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1			0.1	mA
lН	$V_{CC} = 5.5 \text{ V},$	$V_{I} = 2.7 \text{ V}$			20			20	μΑ
I _{IL}	$V_{CC} = 5.5 \text{ V},$	$V_{I} = 0.4 \ V$			-0.5			-0.5	mA
10‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-50		-200	-50		-200	mA
ІССН	V _{CC} = 5.5 V,	V _I = 0		3.5	5		3.5	5	mA
ICCL	V _{CC} = 5.5 V,	V _I = 4.5 V		16	27		16	27	mA

 $[\]frac{1}{1}$ All typical values are at $V_{CC} = 5$ V, $T_A = 25$ °C.

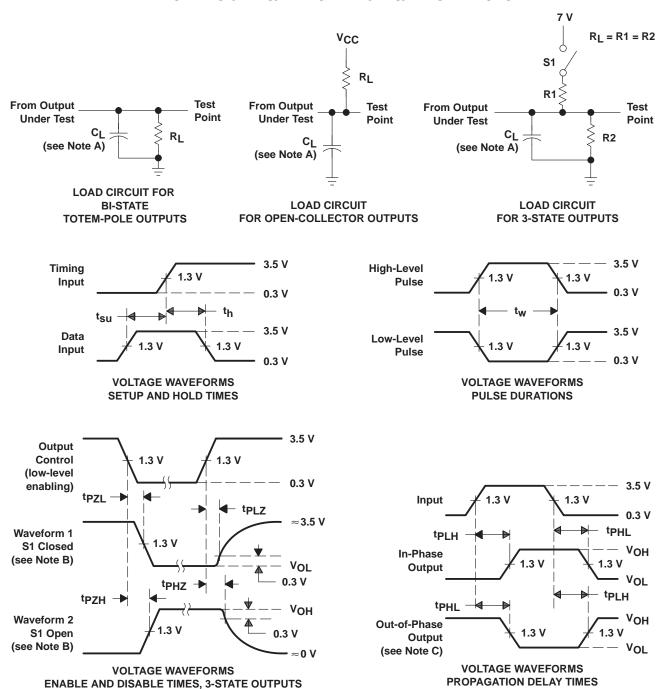
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L R _L T _A	= 50 pF = 500 £ = MIN t	o MAX§		UNIT
			SN54A	S804B	SN74AS	S804B	
			MIN	MAX	MIN	MAX	
t _{PLH}	A or B	V	1	5	1	4	ns
^t PHL	AUID	ſ	1	5	1	4	115

 $[\]S$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- All input pulses have the following characteristics: PRR \leq 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
- The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87766012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87766012A SNJ54AS 804BFK	Samples
5962-8776601RA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8776601RA SNJ54AS804BJ	Samples
5962-8776601SA	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8776601SA SNJ54AS804BW	Samples
5962-88693012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 88693012A SNJ54ALS 804AFK	Samples
5962-8869301RA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8869301RA SNJ54ALS804AJ	Samples
SN54ALS804AJ	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54ALS804AJ	Samples
SN54AS804BJ	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54AS804BJ	Samples
SN74ALS804AN	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS804AN	Samples
SN74AS804BDW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS804B	Samples
SN74AS804BN	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74AS804BN	Samples
SNJ54ALS804AFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 88693012A SNJ54ALS 804AFK	Samples
SNJ54ALS804AJ	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8869301RA SNJ54ALS804AJ	Samples
SNJ54AS804BFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87766012A SNJ54AS 804BFK	Samples

PACKAGE OPTION ADDENDUM

www.ti.com 13-Dec-2022

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54AS804BJ	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8776601RA SNJ54AS804BJ	Samples
SNJ54AS804BW	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8776601SA SNJ54AS804BW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF SN54ALS804A, SN54AS804B, SN74ALS804A, SN74AS804B:

● Catalog: SN74ALS804A, SN74AS804B

• Military: SN54ALS804A, SN54AS804B

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-87766012A	FK	LCCC	20	1	506.98	12.06	2030	NA
5962-8776601SA	W	CFP	20	1	506.98	26.16	6220	NA
5962-88693012A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74ALS804AN	N	PDIP	20	20	506	13.97	11230	4.32
SN74AS804BDW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74AS804BN	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54ALS804AFK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54AS804BFK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54AS804BW	W	CFP	20	1	506.98	26.16	6220	NA

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

 D. Index point is provided on cap for terminal identification only.

 E. Falls within Mil—Std 1835 GDFP2—F20



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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